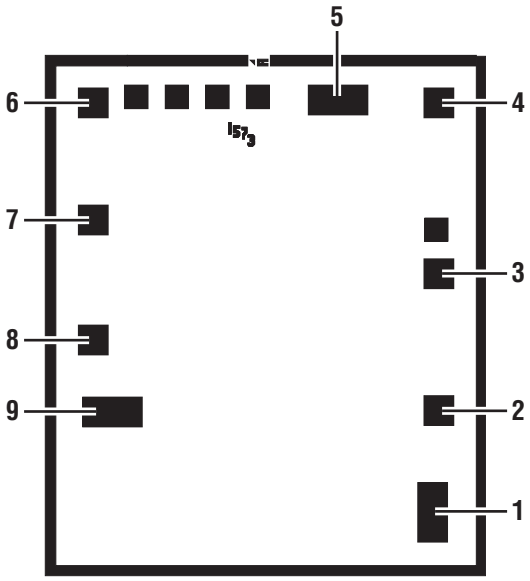
DICE/DWF SPECIFICATION

RH1573K
Low Dropout PNP Regulator Driver



61mils × 72mils,
12mils thick.
†Backside metal: Alloyed gold layer
(K designator)
Backside potential: lowest (GND) voltage

PAD FUNCTION

1. DRIVE
2. V_{IN}
3. V_{OUT}
4. COMP
5. GND1**
6. FB
7. LATCH
8. SHDN
9. GND2**

**GND1 and GND2 are connected together to form GND

DIE CROSS REFERENCE

LTC Finished Part Number	Order Part Number
RH1573K†	RH1573KDICE†
RH1573K†	RH1573KDWF*,†

Please refer to LTC standard product data sheet for other applicable product information.
***DWF = DICE in wafer form.**

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DICE/DWF ELECTRICAL TEST LIMITS T_A = 25°C.

PARAMETER	CONDITIONS	MIN	MAX	UNITS
Reference Voltage	I_{DRIVE} = 20mA, T_J = 25°C	1.252	1.278	V
Line Regulation (V_{FB})	I_{DRIVE} = 20mA, 3V < V_{IN} < 7V		2	mV
Load Regulation (V_{FB})	I_{DRIVE} = 20mA to 250mA		18	mV
FB Pin Bias Current	V_{FB} = 1.265V		4	µA
DRIVE Pin Current	V_{FB} = 1.35V, V_{DRIVE} = 7V V_{FB} = 1.15V, V_{DRIVE} = 1.5V	 290	1.2	mA mA
DRIVE Pin Saturation Voltage	I_{DRIVE} = 20mA, V_{FB} = 1.15V I_{DRIVE} = 250mA, V_{FB} = 1.15V		0.2 1	V V

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DICE/DWF ELECTRICAL TEST LIMITS T_A = 25°C.

PARAMETER	CONDITIONS	MIN	MAX	UNITS
SHDN Pin Threshold Voltage		1	1.5	V
SHDN Pin Current	V_{SHDN} = 5V		300	µA
LATCH Pin Latch-Off Threshold Voltage		1.1	1.8	V
LATCH Pin Charging Current		4	10	µA
LATCH Pin Latching Current			0.85	mA
V_{IN} to V_{OUT} Differential Threshold for Latch Disable		0.55	0.8	V
Input Quiescent Current	V_{IN} = 7V		2.8	mA
Minimum Input Voltage for Bias Operation		2.4		V

Note 1: For circuit operation and application information refer to LT1573 data sheet.

Note 2: For post radiation performance contact factory.

Wafer level testing is performed per the indicated specifications for dice. Considerable differences in performance can often be observed for dice versus packaged units due to the influences of packaging and assembly on certain devices and/or parameters. Please consult factory for more information on dice performance and lot qualifications via lot sampling test procedures.

Dice data sheet subject to change. Please consult factory for current revision in production.

I.D.No. 66-13-rh1573

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LT 0808 • PRINTED IN USA

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